

FRED Module

Fast Recovery Epitaxial Diode

Common Cathode

$$V_{RRM} = 200 \text{ V}$$


$$I_{FAVM} = 356 \text{ A}$$

$$t_{rr} = 150 \text{ ns}$$

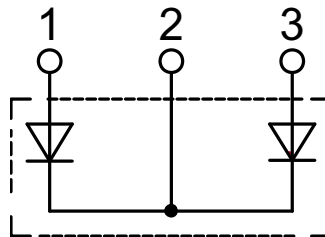
Part number

MEK 350-02DA



 E72873

Backside: isolated



Features / Advantages:

- International standard package with DCB ceramic base plate
- Planar passivated chips
- Short recovery time
- Low switching losses
- Soft recovery behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

Applications:

- Antiparallel diode for high frequency switching devices
- Free wheeling diode in converters and motor control circuits
- Inductive heating and melting
- Uninterruptible power supplies (UPS)
- Ultrasonic cleaners and welders

Package: Y4-M6

- Isolation voltage: 3600 V~
- Industry standard outline
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

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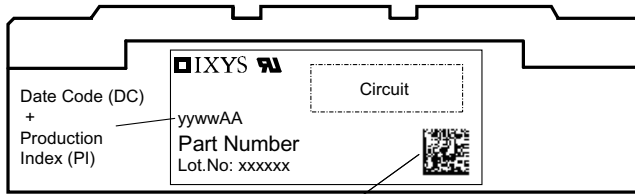


Diode				Ratings			
Symbol	Definitions	Conditions	min.	typ.	max.		
V_{RSM}	max. non-repetitive reverse		$T_{VJ} = 25^{\circ}C$		200	V	
V_{RRM}	max. repetitive reverse		$T_{VJ} = 25^{\circ}C$		200	V	
I_R	reverse current	$V_R = V_{RRM}$ $V_R = 0.8 \cdot V_{RRM}$ $V_R = 0.8 \cdot V_{RRM}$	$T_{VJ} = 25^{\circ}C$		3	mA	
			$T_{VJ} = 25^{\circ}C$		2	mA	
			$T_{VJ} = 125^{\circ}C$		80	mA	
V_F	forward voltage	$I_F = 150 A$	$T_{VJ} = 25^{\circ}C$		0.98	V	
			$T_{VJ} = 125^{\circ}C$		0.80	V	
		$I_F = 260 A$	$T_{VJ} = 25^{\circ}C$		1.07	V	
			$T_{VJ} = 125^{\circ}C$		0.92	V	
I_{FRMS}	RMS forward current		$T_C = 75^{\circ}C$		503	A	
I_{FAV} ①	average forward current	$T_C = 75^{\circ}C$ rectangular, d = 0.5	$T_{VJ} = 150^{\circ}C$		356	A	
V_{TO}	threshold voltage	for power-loss calculations only	$T_{VJ} = T_{VJM}$		0.53	V	
r_T	slope resistance				1.29	m Ω	
R_{thJC}	thermal resistance junction to case			0.085	0.143	K/W	
R_{thCH}	thermal resistance junction to heatsink					K/W	
P_{tot}	total power dissipation		$T_{VJ} = 25^{\circ}C$		875	W	
I_{FSM}	max. surge forward current	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	$T_{VJ} = 45^{\circ}C$		2.40	kA	
					2.64	kA	
			$T_{VJ} = 150^{\circ}C$		2.16	kA	
					2.38	kA	
I^2t	I^2t value for fusing	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	$T_{VJ} = 45^{\circ}C$		28.8	kA ² s	
					29.3	kA ² s	
			$T_{VJ} = 150^{\circ}C$		23.3	kA ² s	
					23.8	kA ² s	
t_{rr}	max. reverse recovery current	$I_F = 350 A$; $-di_F/dt = 200 A/\mu s$	$T_{VJ} = 25^{\circ}C$		60	ns	
			$T_{VJ} = 100^{\circ}C$		150	ns	
I_{RM}	reverse recovery time	$V_R = 100 V$; $L \leq 0.05 \mu H$	$T_{VJ} = 25^{\circ}C$		7	A	
			$T_{VJ} = 100^{\circ}C$		12	A	

① I_{FAVM} rating includes reverse blocking losses at T_{VJM} , $V_R = 0.8 V_{RRM}$, duty cycle d = 0.5

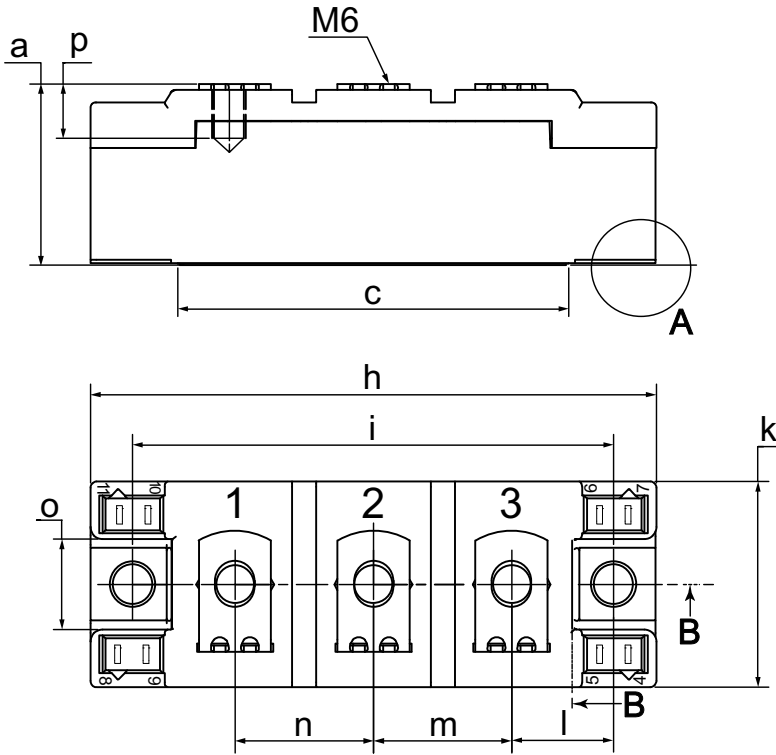


Package Y4-M6				Ratings		
Symbol	Definitions	Conditions	min.	typ.	max.	
I_{RMS}	RMS current	per terminal			300	A
T_{VJ}	virtual junction temperature		-40		150	°C
T_{op}	operation temperature		-40		125	°C
T_{stg}	storage temperature		-40		125	°C
Weight					126	g
M_D	mounting torque		2.25		2.75	Nm
M_T	terminal torque		4.5		5.5	Nm
$d_{Spp/App}$	creepage distance on surface striking distance through air	terminal to terminal	14.0	10.0		mm
$d_{Spb/Apb}$		terminal to backside	16.0	16.0		mm
V_{ISOL}	isolation voltage	t = 1 second t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA		3600 3000	V V

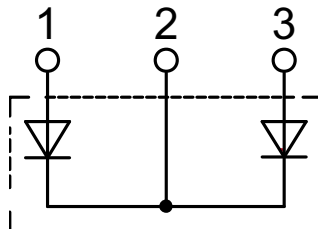
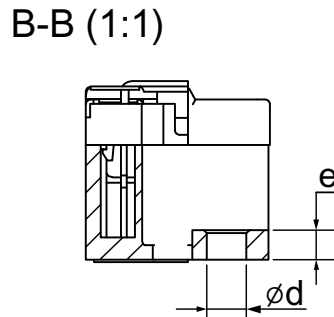
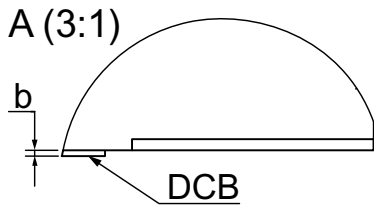


Data Matrix: part no. (1-19), DC + PI (20-25), lot.no.# (26-31), blank (32), serial no.# (33-36)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MEK 350-02DA	MEK 350-02DA	Box	6	464600

Outlines Y4-M6


Dim.	min [mm]	max [mm]	min [inch]	max [inch]
a	30.0	30.6	1.181	1.205
b	typ. 0.25		typ. 0.010	
c	64.0	65.0	2.520	2.559
d	6.5	7.0	0.256	0.275
e	4.9	5.1	0.193	0.201
h	93.5	94.5	3.681	3.720
i	79.5	80.5	3.130	3.169
k	33.4	34.0	1.315	1.339
l	16.7	17.3	0.657	0.681
m	22.7	23.3	0.894	0.917
n	22.7	23.3	0.894	0.917
o	14.0	15.0	0.551	0.591
p	typ. 10.5		typ. 0.413	



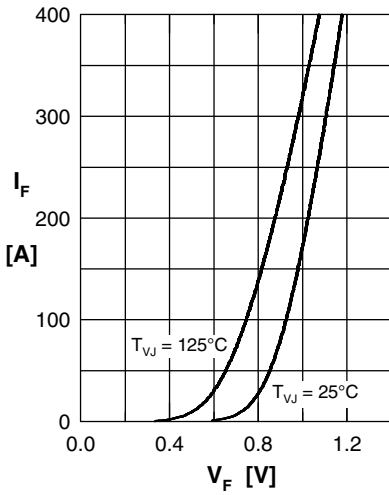
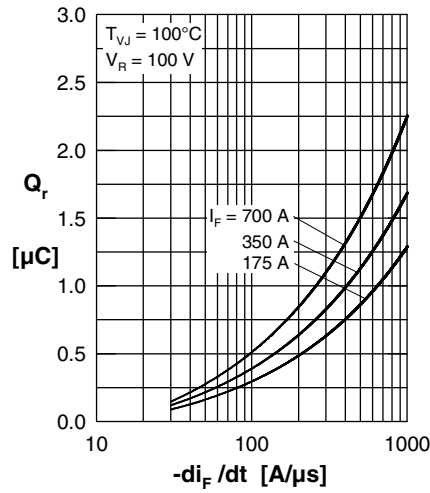
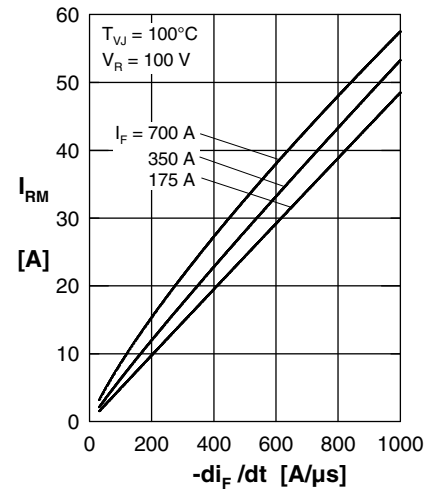
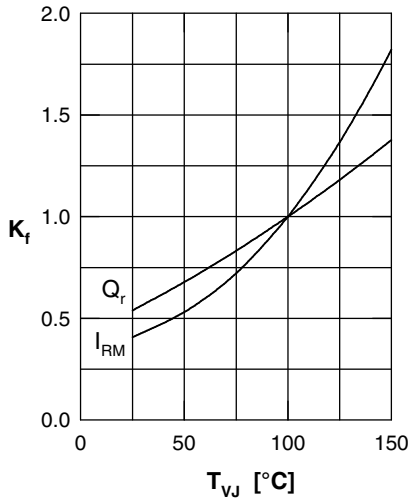
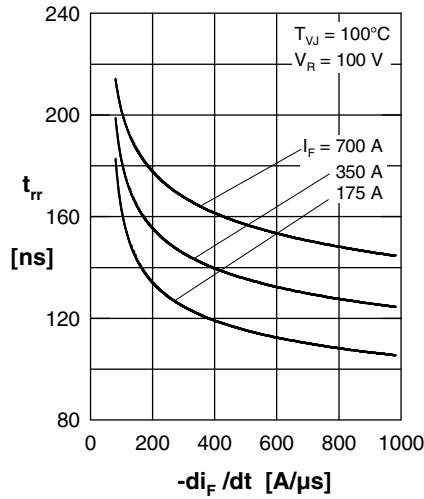
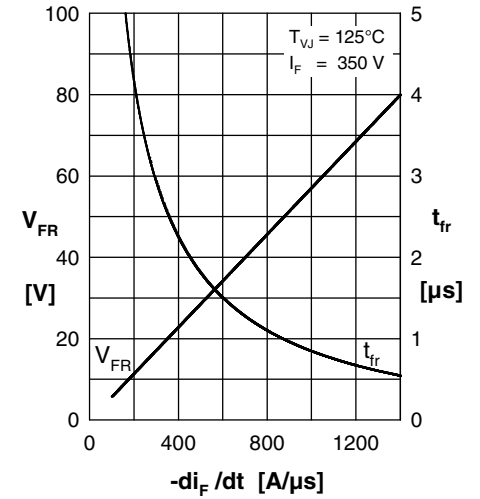
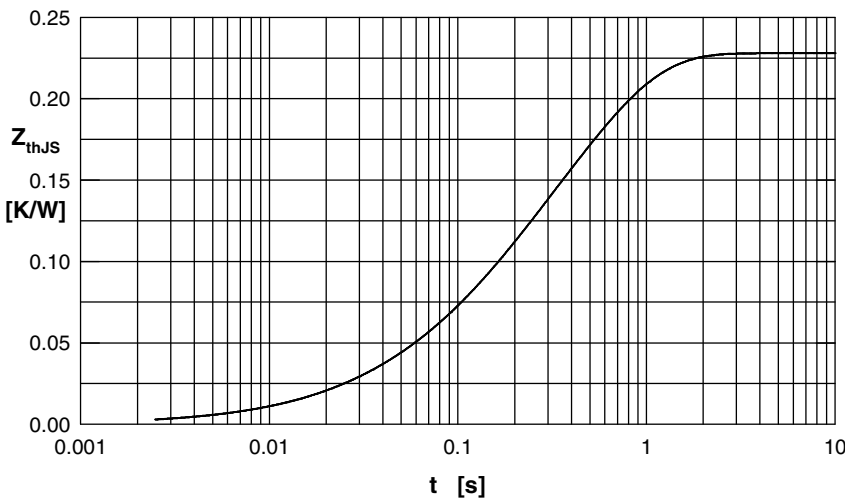
Curves

 Fig. 1 Typ. forward current I_F vs voltage drop V_F per leg

 Fig. 2 Typ. reverse recovery charge Q_r versus $-di_F/dt$

 Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

 Fig. 4 Typ. dynamic parameters Q_r , I_{RM} vs. junction temperature T_{VJ}

 Fig. 5 Typ. recovery time t_{rr} vs. $-di_F/dt$

 Fig. 6 Typ. peak forward voltage V_{FR} und t_{fr} versus $-di_F/dt$


Fig. 7 Typ. transient thermal impedance junction to heatsink

 Constants for Z_{thJS} calculation:

i	R_{thi} [K/W]	t_i [s]
1	0.002	0.080
2	0.008	0.024
3	0.054	0.112
4	0.164	0.464